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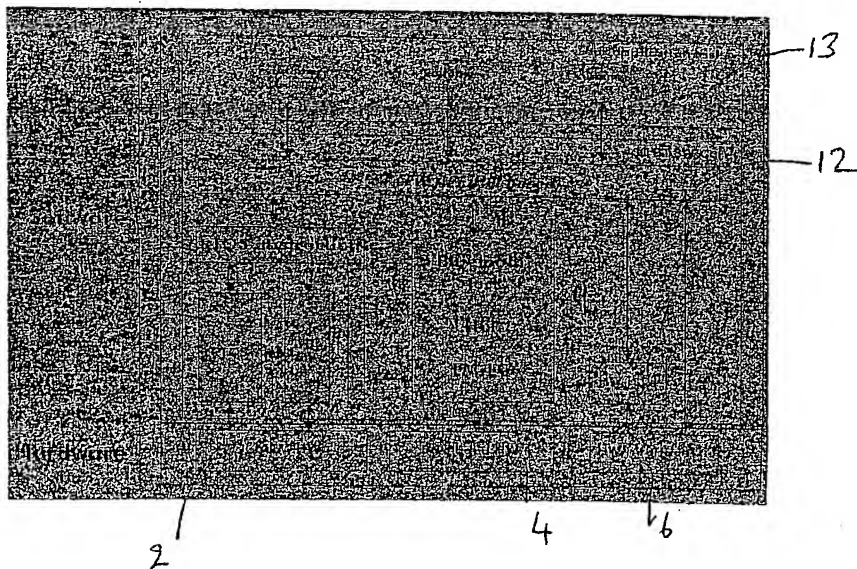
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(54) Title: **CUSTOMER FRAMEWORK FOR EMBEDDED APPLICATIONS**



(57) Abstract: The present invention provides a framework so that software can be embedded into a telecommunications semiconductor device such as an integrated circuit or into a chip. The framework is an API. The telecommunications device may support a telecommunications protocol, e.g. a wireless protocol such as BT. For example the BT Layers above an HCI can support different profiles and/or Applications. The semiconductor devices according to the present invention are particularly suitable for products where no host processor is available to provide the process engine to run the applications software. The semiconductor devices according to the present invention can include an ASIC, an integrated circuit, a multicarrier module (MCM) a printed circuit board or similar. Such devices may find advantageous use in small apparatus, e.g. wireless linked headphones.



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